

IN THE SPECIFICATION

Please replace Paragraph [0022] on Pages 9-10 of the specification with the following:

a1
-- [0022] Other materials may be used instead of the gold layer 24 to provide a wetting layer over the nickel layer 22. Such materials include tin and noble metals such as silver and palladium, or combinations of these metals. Tin, silver, and palladium have melting temperatures of 232°C, 961°C, and 1552°C respectively. It was found that silver with a thickness of approximately 0.2 or less microns is optimal. It may also be possible to make the primary heat spreading structure 20 of other materials such as aluminum, and have nickel plated on the aluminum. Materials other than the pure indium 14 may also be possible, but such a material preferably has a thermal conductivity of at least 35 W/mK, although a thermal conductivity of at least 70 W/mK is much preferred.

IN THE CLAIMS

Please cancel claims 4 and 10 without prejudice.

Please amend the following claims which are pending in the present application:

- a2
1. (Amended) A method of constructing an electronic assembly, comprising:
forming a wetting layer of a material other than nickel on a surface of a thermally conductive heat spreader, the wetting layer being between 0.02 and 3.0